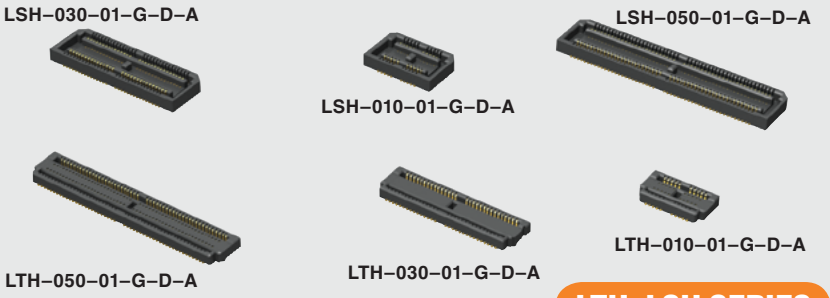
samtec



(0.50 mm) .0197"

LTH, LSH SERIES

LOW-PROFILE BLADE AND BEAM

LTH Mates with:
LSH

LSH Mates with:
LTH

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LTH or www.samtec.com?LSH

Insulator Material:
Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Contact Material:
BeCu
Plating:
Au over 50 µ" (1.27 µm) Ni
Current Rating:
2.6 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max
Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
–01	(2.31) .091

*Processing conditions will affect mated height.

Note: Some lengths, styles and options are non-standard, non-returnable.

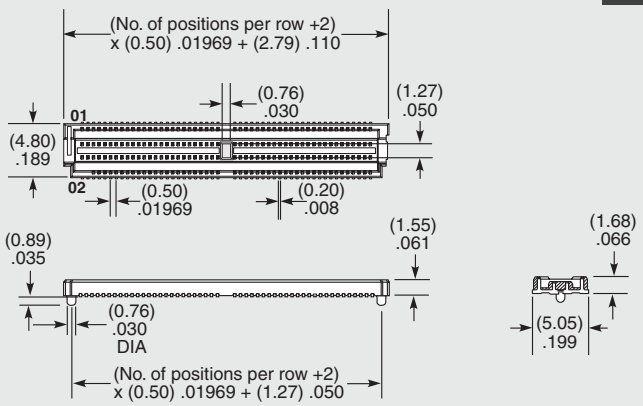
LTH – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

–010, –020, –030, –040, –050

–G = 10 µ" (0.25 µm) Gold

–K = (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad

–TR = Tape and Reel



LSH – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

–010, –020, –030, –040, –050

–G = 10 µ" (0.25 µm) Gold

–K = (7.50 mm) .295" DIA Polyimide Film Pick & Place Pad

–TR = Tape and Reel